



# SOT1349-1

plastic very-very-thin profile fine-pitch ball grid array  
package; 32 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WFBGA32
<b>Package type industry code</b>	WFBGA32
<b>Package style descriptive code</b>	WFBGA (very-very-thin profile fine-pitch ball grid array package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	21-2-2013

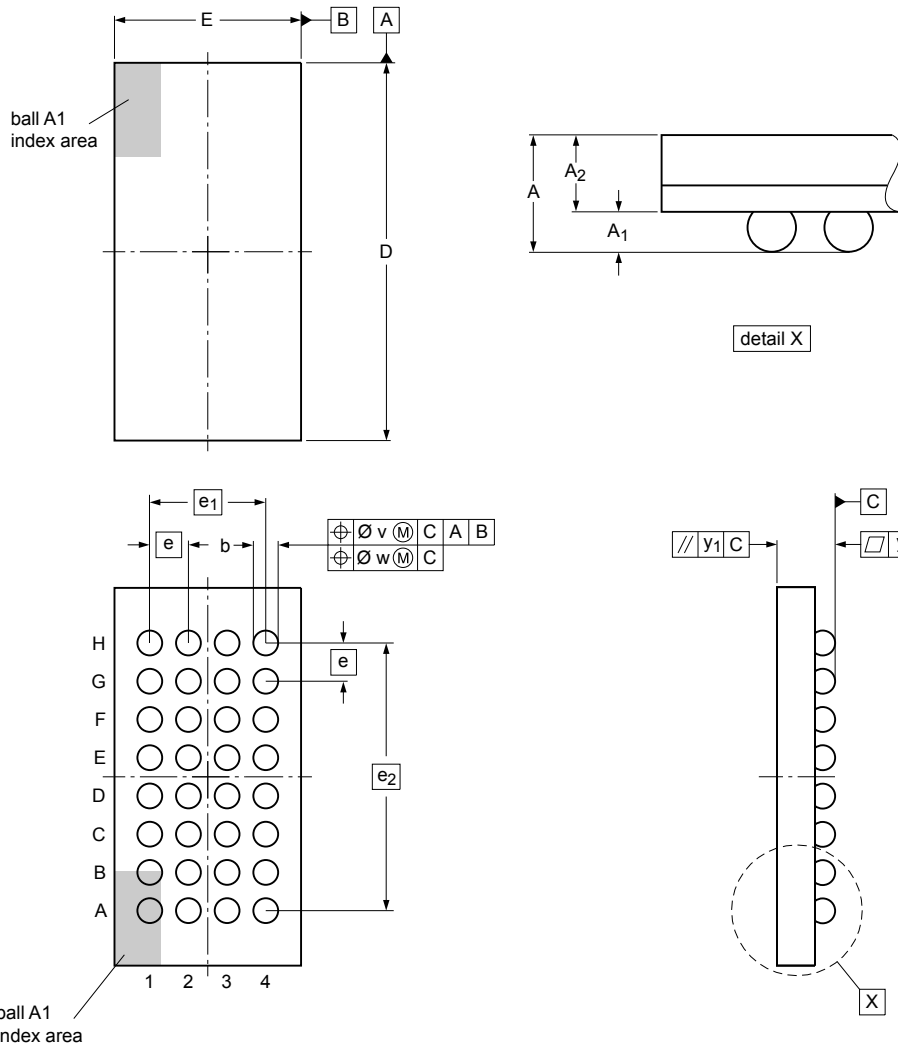
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	3.95	4	mm
E	package width	1.9	-	1.95	2	mm
A	seated height	[tbd]	-	[tbd]	0.7	mm
A <sub>2</sub>	package height	0.35	-	0.4	0.45	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	



2. Package outline

WFBGA32: plastic very-very-thin profile fine-pitch ball grid array package; 32 balls SOT1349-1



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
max	0.7	0.26	0.45	0.30	4.00	2.00							
mm nom		0.21	0.40	0.25	3.95	1.95	0.4	1.2	2.8	0.15	0.05	0.08	0.08
min		0.16	0.35	0.20	3.90	1.90							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline WFBGA32 (SOT1349-1)

### 3. Legal information

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